

## REMARKS

A new abstract and title has been included, as requested by the Examiner.

The Examiner rejected claims 2-4, 8-9, 13-14, 17, 19-20, 23-24, and 26 under 35 U.S.C. Section 102(b) as being anticipated by Schreiber et al., U.S. Patent No. 5,326,412.

Schreiber et al. is directed to the construction of a corrosion resistant barrier for isolated circuitry, as opposed to anything remotely related to probing. The isolated circuit with raised interconnection features has a corrosion resistant gold coating is formed on a reusable stainless steel mandrel which is provided with indentations to define raised features. Conductive layers are electroplated on the mandrel in a pattern of the isolated circuit to be formed. A dielectric substrate is laminated on the conductive layers of the circuit and the circuit is removed from the mandrel.

It may be observed that the raised portions constructed using the mandrel as a support material are symmetrical in nature, as would be expected for forming connective elements used in printed circuits that are connected to one another using the raised portions. In addition, there is no motivation to modify the shape of the raised portions to anything other than a symmetrical shape.

The applicant would further point out that Suzuki et. al., U.S. Patent No. 6,351,885, disclose a method of making conductive dump on a wiring board. In particular FIGS. 11A, 11B, and 11C disclose symmetrical tools having a conical shape or a generally conical

shape. Again, there is no motivation to modify the shape of the tool to anything other than a conical shape for use in constructing the raised portions of Schreiber et al.

Claim 2 patentably distinguishes over Schreiber et al. by claiming creating a first substantially asymmetrical recess within the substrate, as claimed.

Claims 3-30 depend from claim 2, and are patentable for the same reasons asserted for claim 2.

Respectfully submitted,




---

Kevin L. Russell  
Reg. No. 38,292  
Attorneys for Applicant  
Telephone: (503) 227-5631

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail postage prepaid in an envelope addressed to: Mail Stop Patent Application Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on August 25, 2003.

Dated: August 25, 2003



---

Kevin L. Russell